AMENDMENT TO THE CLAIMS

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS

Claim 1 (currently amended): A heat dissipation method for an electronic apparatus comprising a housing, and a circuit board mounted in the housing, the heat dissipation method comprising the steps of:

step 1: providing a heatsink plate having a bottom face rested on a surface of the housing; ~~and~~

step 2: providing a heat conductive plate having a bottom face rested on a top face of the heatsink plate and a top face rested on a bottom face of the circuit board;

step 3: transmitting heat produced by the circuit board to the heatsink plate which is connected to the housing;

step 4: carrying the heat away from the housing.

Claim 2 (original): The heat dissipation method in accordance with claim 1, wherein the heat conductive plate is made of a heat conductive rubber.

Claim 3 (original): The heat dissipation method in accordance with claim 1, wherein the heat conductive plate is made of a heat conductive soft pad.

Claim 4 (original): The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of silver.

Claim 5 (original): The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of aluminum.

Claim 6 (original): The heat dissipation method in accordance with claim 1, wherein each of the housing and the heatsink plate is made of copper.

Claim 7 (original): The heat dissipation method in accordance with claim 1, further comprising the step of providing a heatsink material coated between the surface of the housing and the bottom face of the heatsink plate.

Claim 8 (original): The heat dissipation method in accordance with claim 7, wherein the heatsink material is a heatsink paste.

Claim 9 (original): The heat dissipation method in accordance with claim 1, further comprising the step of providing a heatsink material coated between the top face of the heatsink plate and the bottom face of the heat conductive plate.

Claim 10 (original): The heat dissipation method in accordance with claim 9, wherein the heatsink material is a heatsink paste.

Claim 11 (currently amended): An electronic apparatus comprising:

a housing;

a circuit board mounted in the housing; and

a heatsink device mounted between and rested on the housing and the circuit board;

wherein the heatsink device includes a heatsink plate having a bottom face rested on a surface of the housing, and a heat conductive plate having a bottom face rested on a top face of the heatsink plate and a top face rested on a bottom face of the circuit board;

wherein the heatsink device is used to dissipate heat produced by the circuit board;

wherein the heat produced by the circuit board is transmitted to the heatsink plate which is connected to the housing, and is carried away from the housing.

Claim 12 (canceled).

Claim 13 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein the heatsink device further includes a heatsink material coated between the surface of the housing and the bottom face of the heatsink plate.

Claim 14 (original): The electronic apparatus in accordance with claim 13, wherein the heatsink material is a heatsink paste.

Claim 15 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein the heatsink device further includes a heatsink material coated between the top face of the heatsink plate and the bottom face of the heat conductive plate.

Claim 16 (original): The electronic apparatus in accordance with claim 15, wherein the heatsink material is a heatsink paste.

Claim 17 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein the heat conductive plate is made of a heat conductive rubber or soft pad.

Claim 18 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein each of the housing and the heatsink plate is made of silver.

Claim 19 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein each of the housing and the heatsink plate is made of aluminum.

Claim 20 (currently amended): The electronic apparatus in accordance with claim ~~12~~ 11, wherein each of the housing and the heatsink plate is made of copper.